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# **General Purpose Transistors**

**NPN Silicon** 

## **BC846ALT1G Series**

#### **Features**

- Moisture Sensitivity Level: 1
- ESD Rating Human Body Model: > 4000 V
  - Machine Model: > 400 V
- S and NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

#### **MAXIMUM RATINGS**

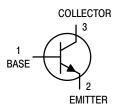
Rating		Symbol	Value	Unit
	BC846 C847, BC850 C848, BC849	V <sub>CEO</sub>	65 45 30	Vdc
	BC846 0847, BC850 0848, BC849	V <sub>CBO</sub>	80 50 30	Vdc
	BC846 0847, BC850 0848, BC849	V <sub>EBO</sub>	6.0 6.0 5.0	Vdc
Collector Current – Continuou	IS	I <sub>C</sub>	100	mAdc

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, (Note 1)  T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	225	mW mW/°C
Thermal Resistance,	р.	556	°C/W
Junction-to-Ambient (Note 1)	$R_{ heta JA}$	550	0/00
Total Device Dissipation Alumina Substrate (Note 2) $T_{\Delta} = 25^{\circ}C$	P <sub>D</sub>	300	mW
Derate above 25°C		2.4	mW/°C
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	417	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

- 1. FR-5 =  $1.0 \times 0.75 \times 0.062$  in.
- 2. Alumina = 0.4  $\times$  0.3  $\times$  0.024 in 99.5% alumina.





SOT-23 CASE 318 STYLE 6

#### **MARKING DIAGRAM**



XX = Device CodeM = Date Code\*= Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or overbar may vary depending upon manufacturing location.

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 12 of this data sheet.

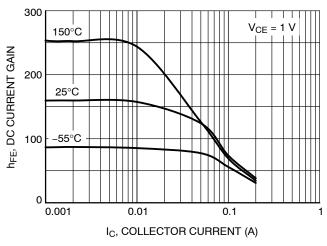
NOTE: Some of the devices on this data sheet have been **DISCONTINUED**. Please refer to the table on page 12.

## **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic			Min	Тур	Max	Unit
OFF CHARACTERISTICS			•		•	•
Collector – Emitter Breakdown Voltage (I <sub>C</sub> = 10 mA)	BC846A, B, C BC847A, B, C, BC850B, C BC848A, B, C, BC849B, C	V <sub>(BR)CEO</sub>	65 45 30	- - -	- - -	V
Collector – Emitter Breakdown Voltage ( $I_C = 10 \mu A, V_{EB} = 0$ )	BC846A, B, C BC847A, B, C BC850B, C BC848A, B, C, BC849B, C	V <sub>(BR)CES</sub>	80 50 30	- - -	- - -	V
Collector – Base Breakdown Voltage ( $I_C = 10 \mu A$ )	BC846A, B, C BC847A, B, C, BC850B, C BC848A, B, C, BC849B, C	V <sub>(BR)CBO</sub>	80 50 30	- - -	- - -	V
Emitter – Base Breakdown Voltage ( $I_E = 1.0 \mu A$ )	BC846A, B, C BC847A, B, C, BC850B, C BC848A, B, C, BC849B, C	V <sub>(BR)EBO</sub>	6.0 6.0 5.0	- - -	- - -	V
Collector Cutoff Current (V <sub>CB</sub> = 30 V) (V <sub>CB</sub> = 30 V, T <sub>A</sub> = 150°C)		I <sub>CBO</sub>	- -	- -	15 5.0	nA μA
ON CHARACTERISTICS						
DC Current Gain ( $I_C = 10 \mu A$ , $V_{CE} = 5.0 V$ )	BC846A, BC847A, BC848A BC846B, BC847B, BC848B BC846C, BC847C, BC848C	h <sub>FE</sub>	- - -	90 150 270	- - -	-
$(I_C = 2.0 \text{ mA}, V_{CE} = 5.0 \text{ V})$	BC846A, BC847A, BC848A BC846B, BC847B, BC848B, BC849B, BC850B		110 200	180 290	220 450	
BC846C, BC	C847C, BC848C, BC849C, BC850C		420	520	800	
Collector – Emitter Saturation Voltage ( $I_C = \frac{1}{2}$ )	10 mA, I <sub>B</sub> = 0.5 mA) 100 mA, I <sub>B</sub> = 5.0 mA)	V <sub>CE(sat)</sub>	- -	_ _	0.25 0.6	V
Base – Emitter Saturation Voltage ( $I_C = 10 \text{ n}$ ) ( $I_C = 100 \text{ m}$ )	nA, I <sub>B</sub> = 0.5 mA) mA, I <sub>B</sub> = 5.0 mA)	V <sub>BE(sat)</sub>	- -	0.7 0.9	- -	V
Base – Emitter Voltage ( $I_C$ = 2.0 mA, $V_{CE}$ = 5.0 V) ( $I_C$ = 10 mA, $V_{CE}$ = 5.0 V)			580 -	660 -	700 770	mV
SMALL-SIGNAL CHARACTERISTICS				-		
Current – Gain – Bandwidth Product ( $I_C = 10$ mA, $V_{CE} = 5.0$ Vdc, $f = 100$ MHz)			100	_	-	MHz
Output Capacitance (V <sub>CB</sub> = 10 V, f = 1.0 MHz)			_	-	4.5	pF
OL	Noise Figure ( $I_C$ = 0.2 mA, $V_{CE}$ = 5.0 Vdc, $R_S$ = 2.0 k $\Omega$ , BC846A,B,C, BC847A,B,C, BC848A,B,C			_ _	10 4.0	dB

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### BC846A, BC847A, BC848A, SBC846A



300 150°C VCE = 5 V VCE = 5 V VCE = 5 V 0 0.001 0.01 0.1 IC, COLLECTOR CURRENT (A)

Figure 1. DC Current Gain vs. Collector Current

Figure 2. DC Current Gain vs. Collector Current

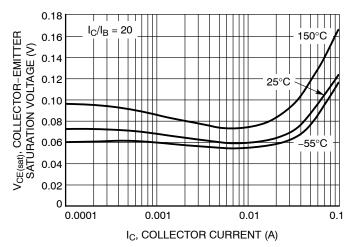


Figure 3. Collector Emitter Saturation Voltage vs. Collector Current

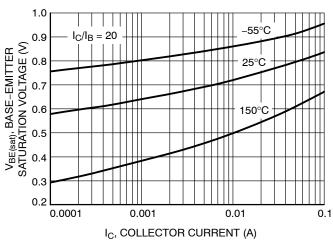


Figure 4. Base Emitter Saturation Voltage vs.
Collector Current

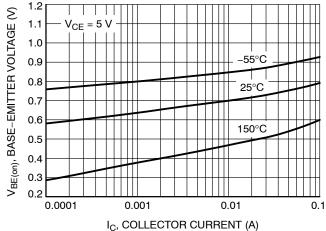
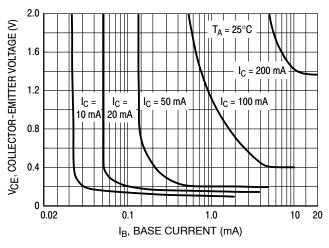


Figure 5. Base Emitter Voltage vs. Collector Current

### BC846A, BC847A, BC848A, SBC846A



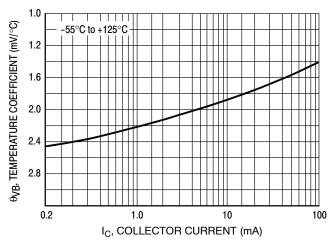


Figure 6. Collector Saturation Region

Figure 7. Base-Emitter Temperature Coefficient

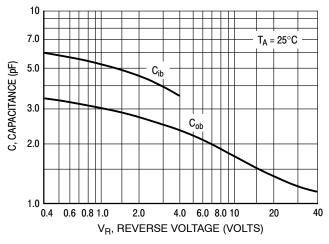


Figure 8. Capacitances

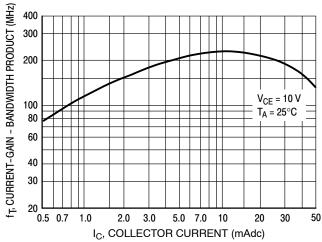


Figure 9. Current-Gain - Bandwidth Product

#### BC846B, SBC846B

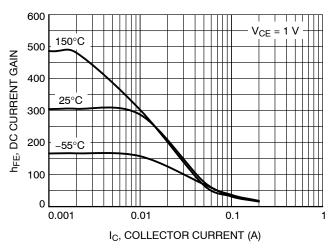


Figure 10. DC Current Gain vs. Collector Current

Figure 11. DC Current Gain vs. Collector Current

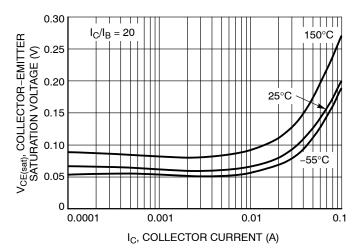
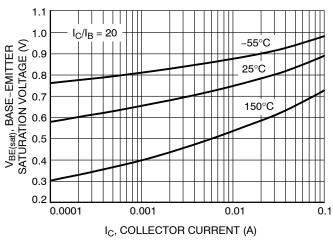


Figure 12. Collector Emitter Saturation Voltage vs. Collector Current





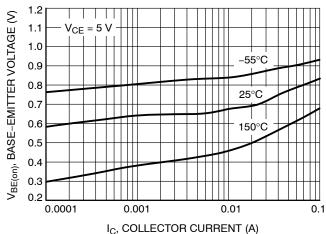
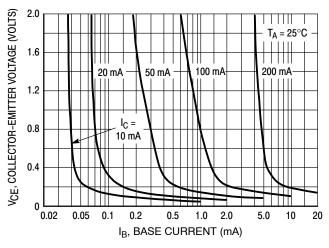


Figure 14. Base Emitter Voltage vs. Collector Current

## BC846B, SBC846B



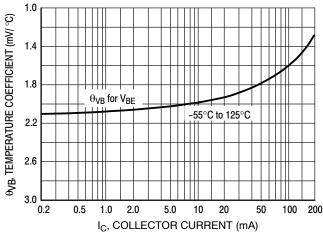


Figure 15. Collector Saturation Region

Figure 16. Base-Emitter Temperature Coefficient

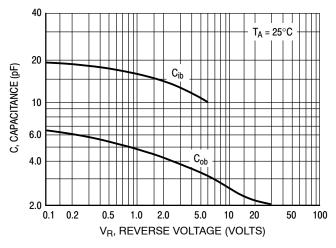


Figure 17. Capacitance

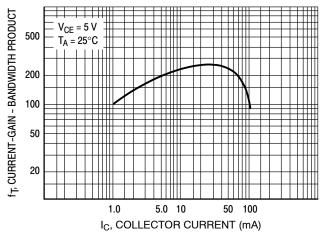
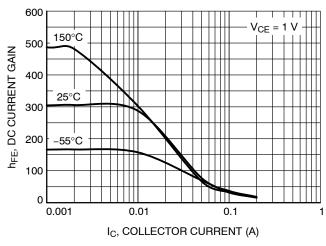


Figure 18. Current-Gain - Bandwidth Product

#### BC847B, BC848B, BC849B, BC850B, SBC847B, SBC848B



600  $V_{CE} = 5 V$ 150°C 500 hFE, DC CURRENT GAIN 400 25°C 300 200 -55°C 100 0 0.001 0.01 0.1 I<sub>C</sub>, COLLECTOR CURRENT (A)

Figure 19. DC Current Gain vs. Collector Current

Figure 20. DC Current Gain vs. Collector Current

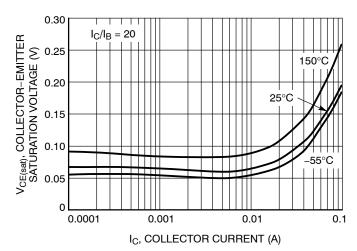


Figure 21. Collector Emitter Saturation Voltage vs. Collector Current

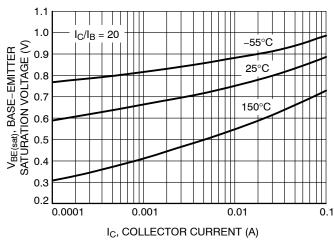


Figure 22. Base Emitter Saturation Voltage vs.
Collector Current

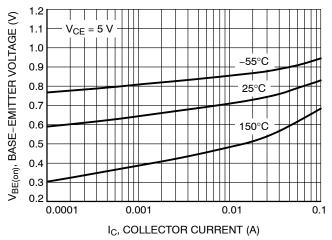


Figure 23. Base Emitter Voltage vs. Collector Current

## BC847B, BC848B, BC849B, BC850B, SBC846B, SBC847B, SBC848B

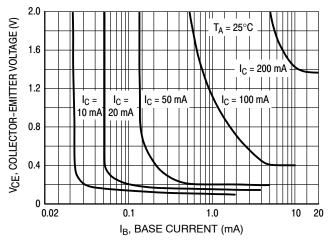


Figure 24. Collector Saturation Region

Figure 25. Base–Emitter Temperature Coefficient

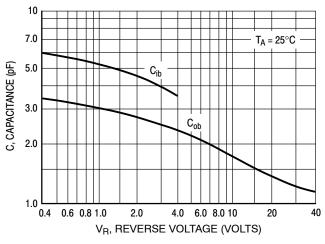


Figure 26. Capacitances

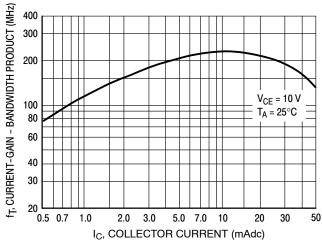
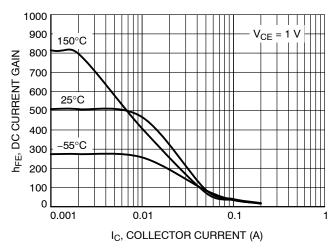


Figure 27. Current-Gain - Bandwidth Product

## BC846C, BC847C, BC848C, BC849C, BC850C, SBC847C



1000 900 150°C 800 hFE, DC CURRENT GAIN 700 600 25°C 500 400 -55°C 300 200 100 0.001 0.01 0.1 IC, COLLECTOR CURRENT (A)

Figure 28. DC Current Gain vs. Collector Current

Figure 29. DC Current Gain vs. Collector Current

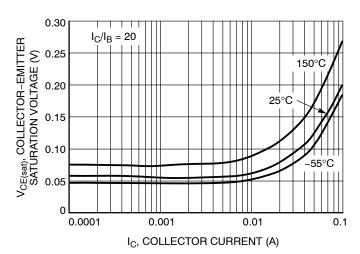
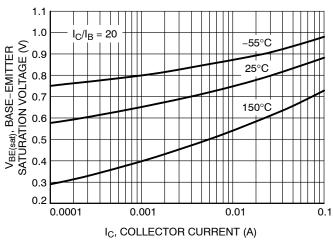


Figure 30. Collector Emitter Saturation Voltage vs. Collector Current





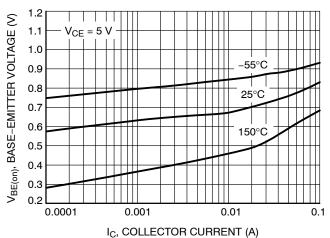


Figure 32. Base Emitter Voltage vs. Collector Current

## BC846C, BC847C, BC848C, BC849C, BC850C, SBC847C

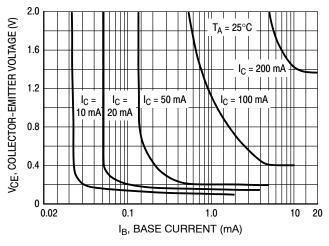


Figure 33. Collector Saturation Region

Figure 34. Base–Emitter Temperature Coefficient

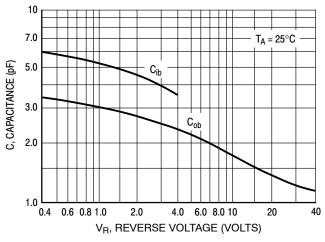


Figure 35. Capacitances

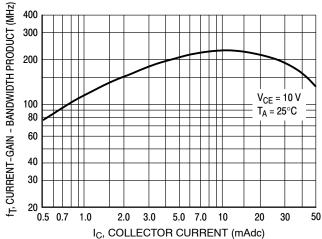


Figure 36. Current-Gain - Bandwidth Product

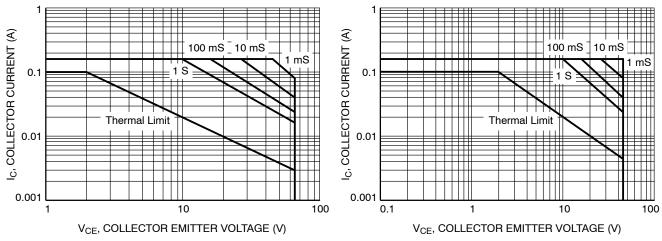


Figure 37. Safe Operating Area for BC846A, BC846B, BC846C

Figure 38. Safe Operating Area for BC847A, BC847B, BC847C, BC850B, BC850C

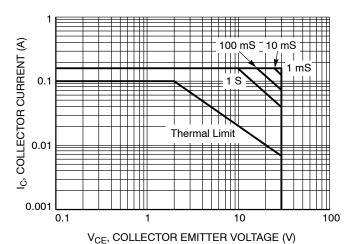


Figure 39. Safe Operating Area for BC848A, BC848B, BC848C, BC849B, BC849C

#### **ORDERING INFORMATION**

Device	Marking	Package	Shipping <sup>†</sup>
BC846ALT1G			
SBC846ALT1G*	1A		3,000 / Tape & Reel
BC846ALT3G			10,000 / Tape & Reel
BC846BLT1G			0.000 / T
SBC846BLT1G*	4.0		3,000 / Tape & Reel
BC846BLT3G	1B		40.000 /T
SBC846BLT3G*			10,000 / Tape & Reel
BC846CLT1G	3C		3,000 / Tape & Reel
BC847ALT1G	1E		3,000 / Tape & Reel
BC847BLT1G			0.000 / T
SBC847BLT1G*			3,000 / Tape & Reel
BC847BLT3G	1F		
NSVBC847BLT3G*		SOT-23 (Pb-Free)	10,000 / Tape & Reel
BC847CLT1G			
SBC847CLT1G*	1G		3,000 / Tape & Reel
BC847CLT3G		(. 2 )	10,000 / Tape & Reel
BC848ALT1G	1J		3,000 / Tape & Reel
BC848BLT1G			0.000 / T
SBC848BLT1G*	1K		3,000 / Tape & Reel
BC848BLT3G			10,000 / Tape & Reel
BC848CLT1G			0.000 / T
NSVBC848CLT1G*	1L		3,000 / Tape & Reel
BC848CLT3G			10,000 / Tape & Reel
BC849BLT1G	2B		3,000 / Tape & Reel
BC849CLT1G	2C		3,000 / Tape & Reel
BC850BLT1G	25		
NSVBC850BLT1G*	2F		0.000 (Texas 9. Dead
BC850CLT1G	200		3,000 / Tape & Reel
NSVBC850CLT1G*	2G		

### **DISCONTINUED** (Note 3)

BC847ALT3G	1E	SOT-23 (Pb-Free)	10,000 / Tape & Reel
NSVBC849BLT1G*	O.D.		3,000 / Tape & Reel
BC849BLT3G	2B		10,000 / Tape & Reel
BC849CLT3G	2C		10,000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup>S and NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

<sup>3.</sup> **DISCONTINUED:** These devices are not recommended for new design. Please contact your **onsemi** representative for information. The most current information on these devices may be available on <a href="https://www.onsemi.com">www.onsemi.com</a>.

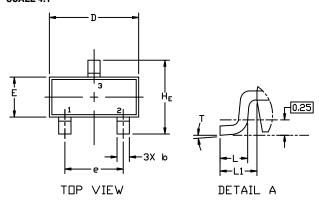


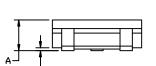


SOT-23 (TO-236) **CASE 318 ISSUE AT** 

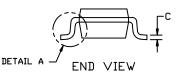
**DATE 01 MAR 2023** 

## SCALE 4:1





SIDE VIEW



#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
- CONTROLLING DIMENSION: MILLIMETERS
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIM	MILLIMETERS			INCHES	
DIM	MIN.	N□M.	MAX.	MIN.	N□M.	MAX.
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	0*		10°	0*		10°

### **GENERIC MARKING DIAGRAM\***

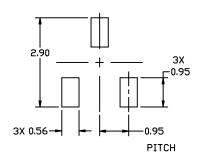


XXX = Specific Device Code

= Date Code

= Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.



#### RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

#### **STYLES ON PAGE 2**

DOCUMENT NUMBER:	98ASB42226B	Electronic versions are uncontrolled except when accessed directly from the Document Reportant versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	SOT-23 (TO-236)		PAGE 1 OF 2	

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#### **SOT-23 (TO-236)** CASE 318 ISSUE AT

**DATE 01 MAR 2023** 

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE	1	
STYLE 9:	STYLE 10:	STYLE 11: PIN 1. ANODE 2. CATHODE 3. CATHODE-ANODE	STYLE 12:	STYLE 13:	STYLE 14:
PIN 1. ANODE	PIN 1. DRAIN		PIN 1. CATHODE	PIN 1. SOURCE	PIN 1. CATHODE
2. ANODE	2. SOURCE		2. CATHODE	2. DRAIN	2. GATE
3. CATHODE	3. GATE		3. ANODE	3. GATE	3. ANODE
STYLE 15:	STYLE 16:	STYLE 17:	STYLE 18:	STYLE 19:	STYLE 20:
PIN 1. GATE	PIN 1. ANODE	PIN 1. NO CONNECTION	PIN 1. NO CONNECTION	I PIN 1. CATHODE	PIN 1. CATHODE
2. CATHODE	2. CATHODE	2. ANODE	2. CATHODE	2. ANODE	2. ANODE
3. ANODE	3. CATHODE	3. CATHODE	3. ANODE	3. CATHODE-ANODE	3. GATE
STYLE 21:	STYLE 22:	STYLE 23:	STYLE 24:	STYLE 25:	STYLE 26:
PIN 1. GATE	PIN 1. RETURN	PIN 1. ANODE	PIN 1. GATE	PIN 1. ANODE	PIN 1. CATHODE
2. SOURCE	2. OUTPUT	2. ANODE	2. DRAIN	2. CATHODE	2. ANODE
3. DRAIN	3. INPUT	3. CATHODE	3. SOURCE	3. GATE	3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE				

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